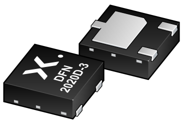


PBSS5250PAS-Q

50 V, 2 A PNP low VCEsat transistor

16 May 2024

Product data sheet

1. General description

PNP low V_{CEsat} transistor in a DFN2020D-3 (SOT1061D) leadless small Surface-Mounted Device (SMD) plastic package.

2. Features and benefits

- Low collector-emitter saturation voltage V_{CEsat}
- High collector current capability: I_C and I_{CM}
- Higher efficiency leading to less heat generation
- Reduced printed-circuit board requirements
- Leadless small SMD plastic package with solderable side pads
- Exposed heat sink for excellent thermal and electrical conductivity
- Suitable for Automatic Optical Inspection (AOI) of solder joint
- Qualified according to AEC-Q101 and recommended for use in automotive applications

3. Applications

- Loadswitch
  - Battery-driven devices
  - Power management
  - Charging circuits
  - Power switches (e.g. motors, fans)

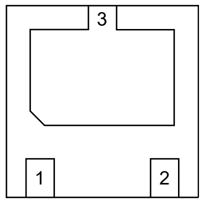
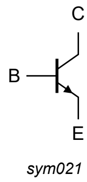
4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{CEO}	collector-emitter voltage	open base		-	-	-50	V
I_C	collector current			-	-	-2	A
h_{FE}	DC current gain	V_{CE} = -2 V; I_C = -0.1 A; T_{amb} = 25 °C		200	-	-	

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	B	base	 Transparent top view **DFN2020D-3 (SOT1061D)**	
2	E	emitter		
2	C	collector		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PBSS5250PAS-Q	DFN2020D-3	plastic, leadless thermal enhanced ultra thin small outline package with side-wettable flanks (SWF); no leads; 3 terminals; 1.3 mm pitch; 2 mm x 2 mm x 0.65 mm body	SOT1061D

7. Marking

Table 4. Marking codes

Type number	Marking code
PBSS5250PAS-Q	G5

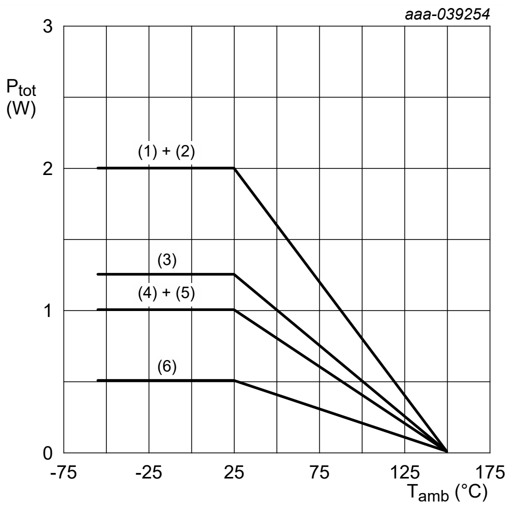
8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{CBO}	collector-base voltage	open emitter		-	-50	V
V_{CEO}	collector-emitter voltage	open base		-	-50	V
V_{EBO}	emitter-base voltage	open collector		-	-5	V
I_C	collector current			-	-2	A
I_{CM}	peak collector current	limited by $T_{j(max)}$		-	-5	A
I_B	base current			-	-0.5	A
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C	[1]	-	0.5	W
			[2] [3]	-	1	W
			[4]	-	1.2	W
			[5] [6]	-	2	W
T_j	junction temperature			-	150	°C
T_{amb}	ambient temperature			-65	150	°C
T_{stg}	storage temperature			-65	150	°C

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 1 cm^2.
[3] Device mounted on an FR4 PCB, 4-layer copper, tin-plated and standard footprint.
[4] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 6 cm^2.
[5] Device mounted on a ceramic PCB, Al_2O_3, standard footprint.
[6] Device mounted on a FR4 PCB, 4-layer copper, tin-plated and mounting pad for collector 1 cm^2.



(1) Ceramic PCB, single-sided copper, standard footprint
(2) FR4 PCB, 4-layer copper, 1 cm^2
(3) FR4 PCB, single-sided copper, 6 cm^2
(4) FR4 PCB, single-sided copper, 1 cm^2
(5) FR4 PCB, 4-layer copper, standard footprint
(6) FR4 PCB, single-sided copper, standard footprint

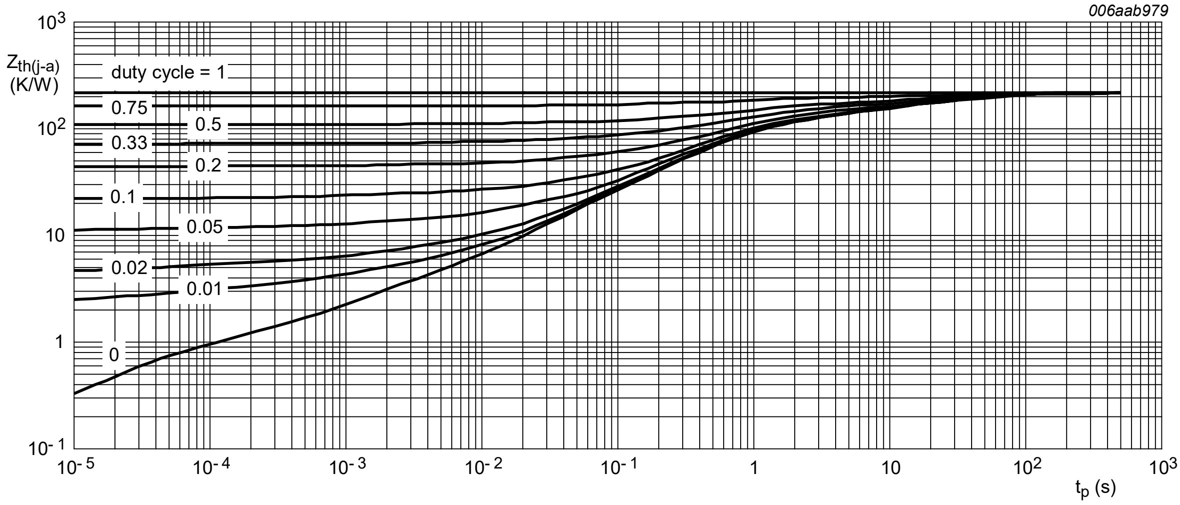
Fig. 1. Power derating curves

9. Thermal characteristics

Table 6. Thermal characteristics

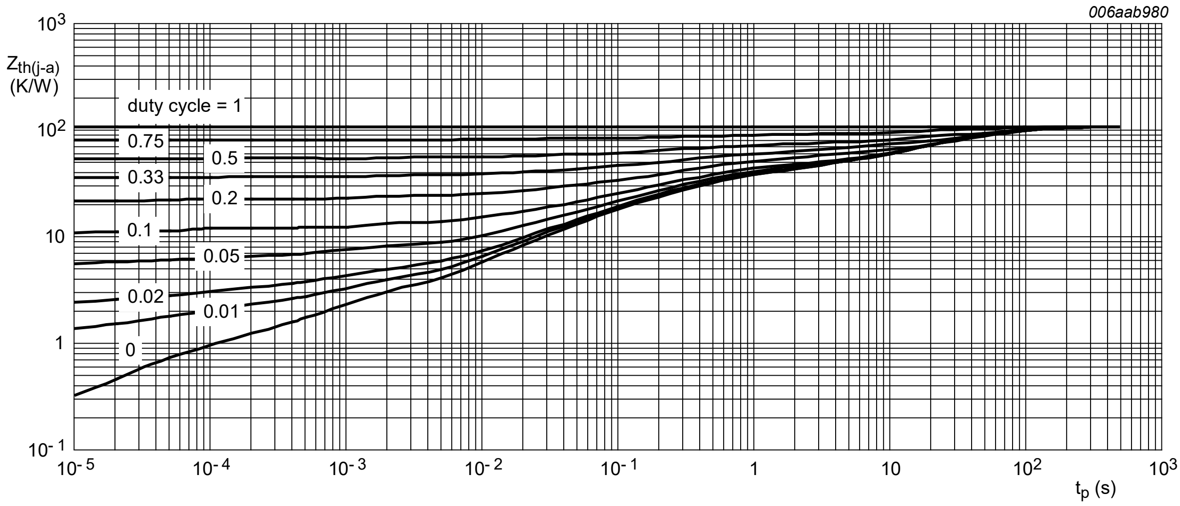
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	-	250	K/W
			[2] [3]	-	-	125	K/W
			[4]	-	-	100	K/W
			[5] [6]	-	-	60	K/W

[1] Device mounted on an FR4 PCB, single-sided, 35 µm copper, tin-plated and standard footprint.
[2] Device mounted on an FR4 PCB, single-sided, 35 µm copper, tin-plated, mounting pad for collector 1 cm^2.
[3] Device mounted on an FR4 PCB, 4-layer copper, tin-plated and standard footprint.
[4] Device mounted on an FR4 PCB, single-sided, 35 µm copper, tin-plated, mounting pad for collector 6 cm^2.
[5] Device mounted on a ceramic PCB, Al_2O_3, standard footprint.
[6] Device mounted on an FR4 PCB, 4-layer copper, tin-plated and mounting pad for collector 1 cm^2.



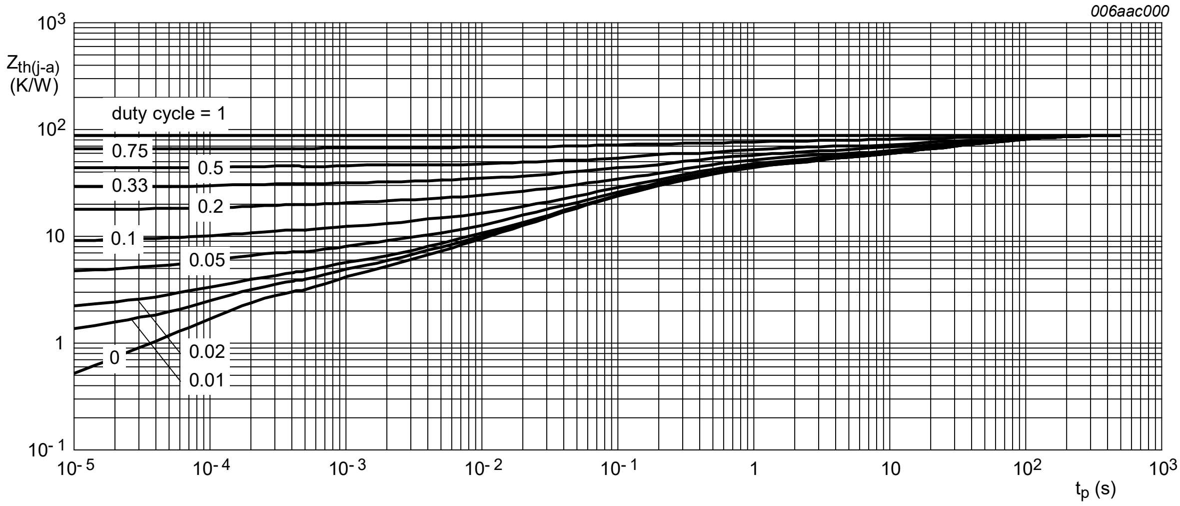
FR4 PCB, standard footprint

Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



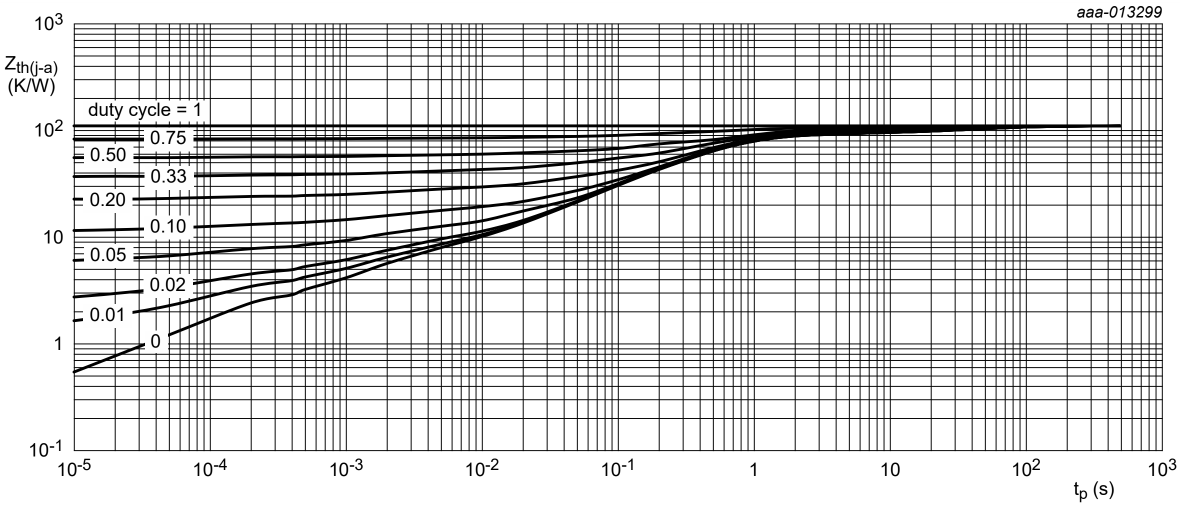
FR4 PCB, mounting pad for collector 1 cm^2

Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



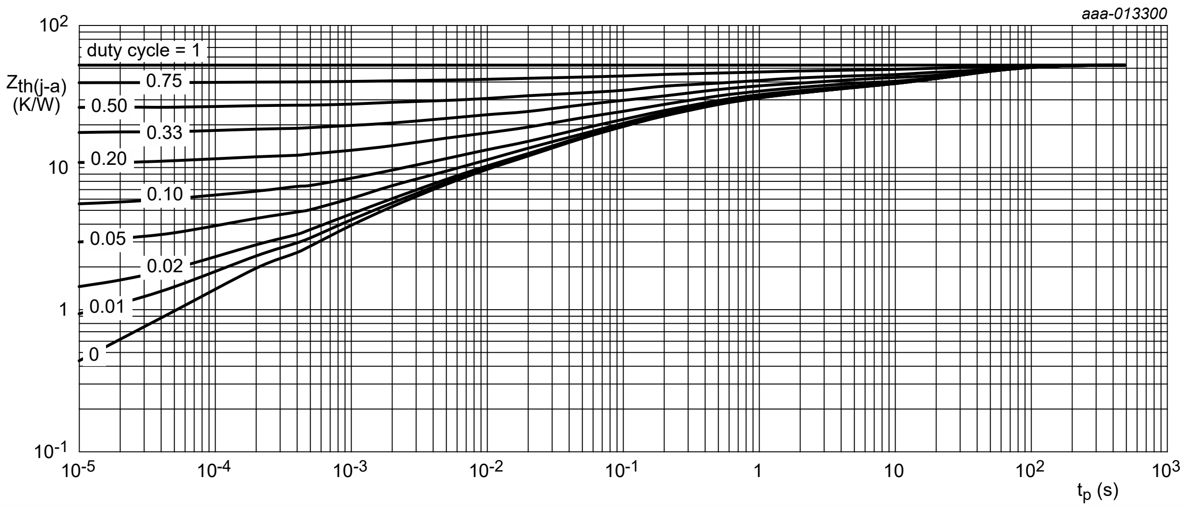
FR4 PCB, mounting pad for collector 6 cm^2

Fig. 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



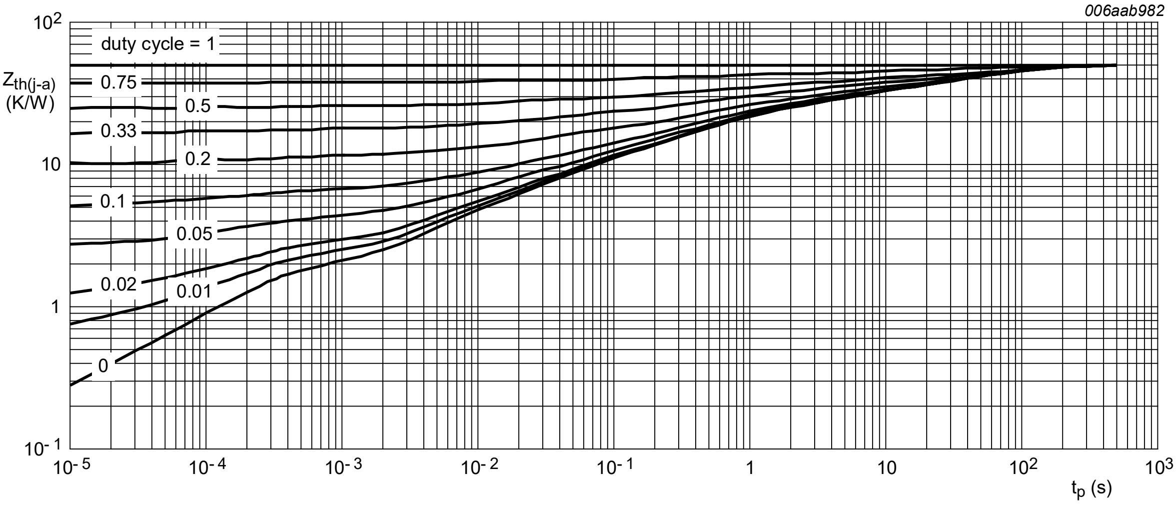
FR4 PCB, 4-layer copper, standard footprint

Fig. 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, 4-layer copper, mounting pad for collector 1 cm^2

Fig. 6. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



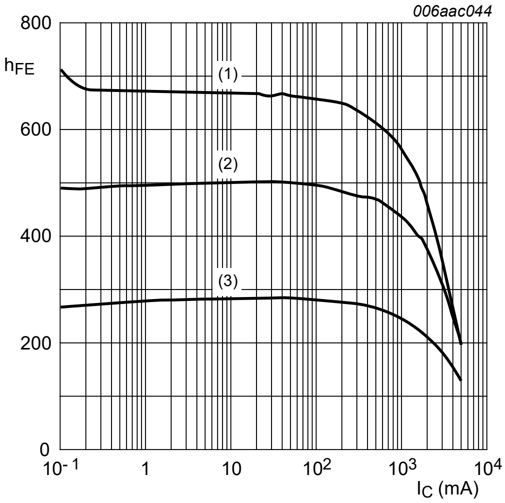
Ceramic PCB, Al_2O_3, standard footprint

Fig. 7. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

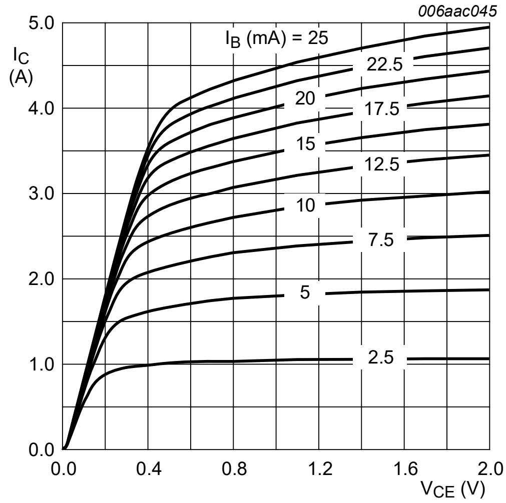
Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$V_{(BR)CBO}$	collector-base breakdown voltage	I_C = -100 µA; I_E = 0 A; T_{amb} = 25 °C		-50	-	-	V
$V_{(BR)CEO}$	collector-emitter breakdown voltage	I_C = -2 mA; I_B = 0 A; T_{amb} = 25 °C		-50	-	-	V
$V_{(BR)EBO}$	emitter-base breakdown voltage (collector open)	I_E = -100 µA; I_C = 0 A; T_{amb} = 25 °C		-5	-	-	V
I_{CBO}	collector-base cut-off current	V_{CB} = -50 V; I_E = 0 A; T_{amb} = 25 °C		-	-	-100	nA
		V_{CB} = -50 V; I_E = 0 A; T_j = 150 °C		-	-	-50	µA
I_{EBO}	emitter-base cut-off current	V_{EB} = -5 V; I_C = 0 A; T_{amb} = 25 °C		-	-	-100	nA
I_{CES}	collector-emitter cut-off current	V_{CE} = -50 V; V_{BE} = 0 V; T_{amb} = 25 °C		-	-	-100	nA
h_{FE}	DC current gain	V_{CE} = -2 V; I_C = -0.1 A; T_{amb} = 25 °C		200	-	-	
		V_{CE} = -2 V; I_C = -0.5 A; T_{amb} = 25 °C		200	-	-	
		V_{CE} = -2 V; I_C = -1 A; pulsed; t_p ≤ 300 µs; δ ≤ 0.02; T_{amb} = 25 °C		200	-	-	
		V_{CE} = -2 V; I_C = -2 A; pulsed; t_p ≤ 300 µs; δ ≤ 0.02; T_{amb} = 25 °C		100	-	-	
V_{CEsat}	collector-emitter saturation voltage	I_C = -0.5 A; I_B = -50 mA; T_{amb} = 25 °C		-	-	-90	mV
		I_C = -1 A; I_B = -50 mA; T_{amb} = 25 °C		-	-	-250	mV
		I_C = -2 A; I_B = -100 mA; T_{amb} = 25 °C		-	-	-380	mV
		I_C = -2 A; I_B = -200 mA; pulsed; t_p ≤ 300 µs; δ ≤ 0.02; T_{amb} = 25 °C		-	-	-320	mV
R_{CEsat}	collector-emitter saturation resistance			-	-	160	mΩ
V_{BEsat}	base-emitter saturation voltage	I_C = -2 A; I_B = -100 mA; T_{amb} = 25 °C		-	-	-1.1	V
V_{BEon}	base-emitter turn-on voltage	V_{CE} = -2 V; I_C = -1 A; T_{amb} = 25 °C		-1.1	-	-	V
f_T	transition frequency	V_{CE} = -5 V; I_C = -100 mA; f = 100 MHz; T_{amb} = 25 °C		100	-	-	MHz
C_c	collector capacitance	V_{CB} = -10 V; I_E = 0 A; i_e = 0 A; f = 1 MHz; T_{amb} = 25 °C		-	-	35	pF



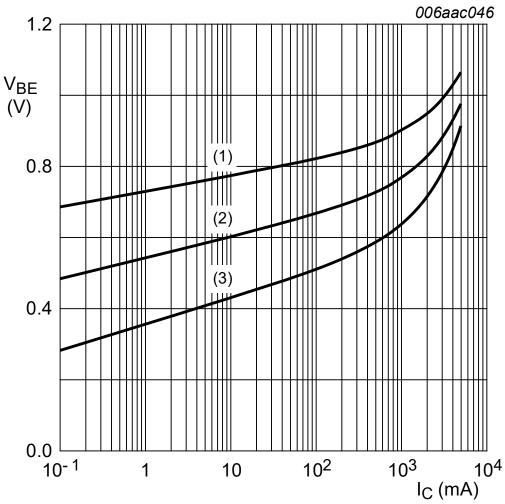
V_{CE} = 2 V
(1) T_{amb} = 100 °C
(2) T_{amb} = 25 °C
(3) T_{amb} = −55 °C

Fig. 8. DC current gain as a function of collector current; typical values



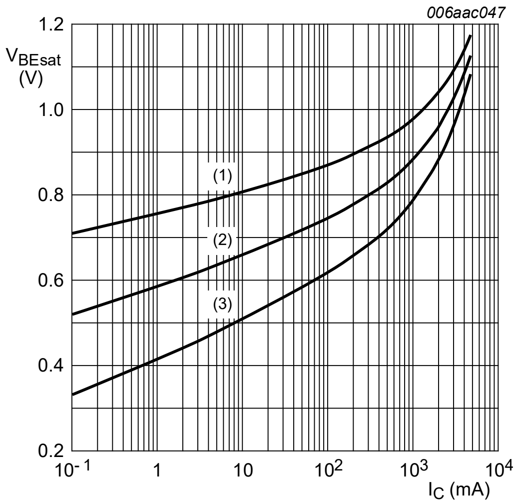
T_{amb} = 25 °C

Fig. 9. Collector current as a function of collector-emitter voltage; typical values



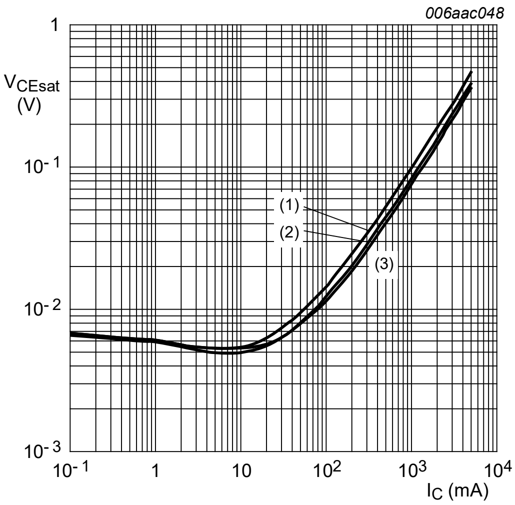
V_{CE} = 2 V
(1) T_{amb} = −55 °C
(2) T_{amb} = 25 °C
(3) T_{amb} = 100 °C

Fig. 10. Base-emitter voltage as a function of collector current; typical values



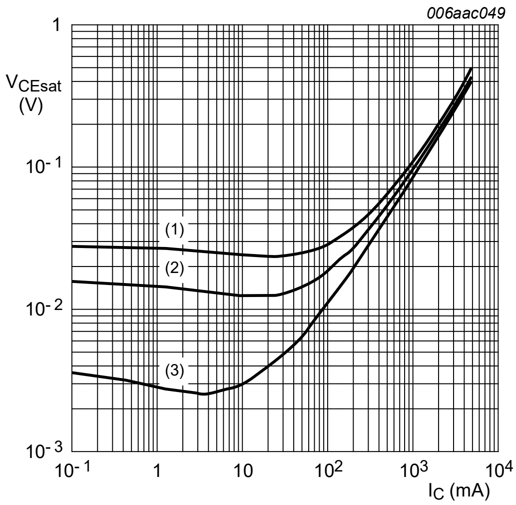
I_C/I_B = 20
(1) T_{amb} = −55 °C
(2) T_{amb} = 25 °C
(3) T_{amb} = 100 °C

Fig. 11. Base-emitter saturation voltage as a function of collector current; typical values



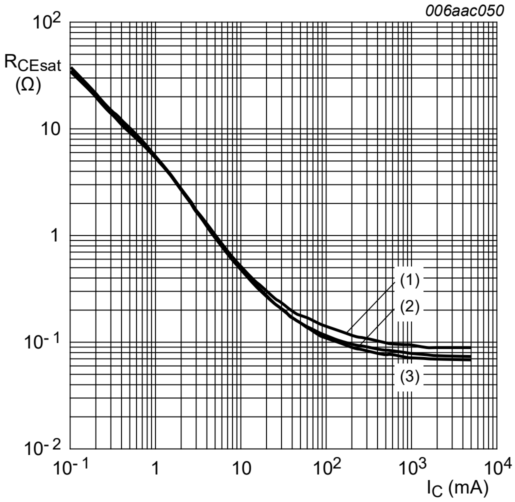
$I_C/I_B = 20$
(1) $T_{amb} = 100$ °C
(2) $T_{amb} = 25$ °C
(3) $T_{amb} = -55$ °C

Fig. 12. Collector-emitter saturation voltage as a function of collector current; typical values



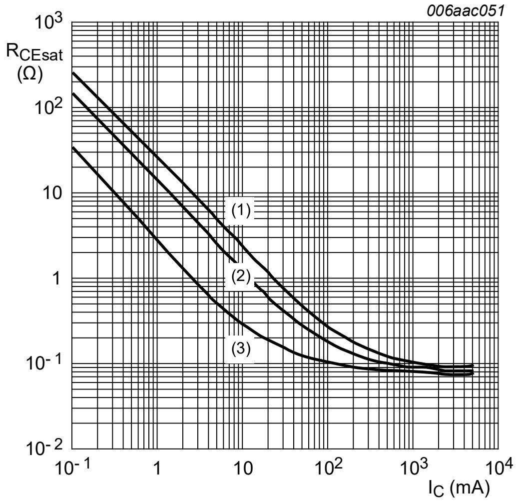
$T_{amb} = 25$ °C
(1) $I_C/I_B = 100$
(2) $I_C/I_B = 50$
(3) $I_C/I_B = 10$

Fig. 13. Collector-emitter saturation voltage as a function of collector current; typical values



$I_C/I_B = 20$
(1) $T_{amb} = 100$ °C
(2) $T_{amb} = 25$ °C
(3) $T_{amb} = -55$ °C

Fig. 14. Collector-emitter saturation resistance as a function of collector current; typical values



$T_{amb} = 25$ °C
(1) $I_C/I_B = 100$
(2) $I_C/I_B = 50$
(3) $I_C/I_B = 10$

Fig. 15. Collector-emitter saturation resistance as a function of collector current; typical values

11. Test information

Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - *Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

12. Package outline

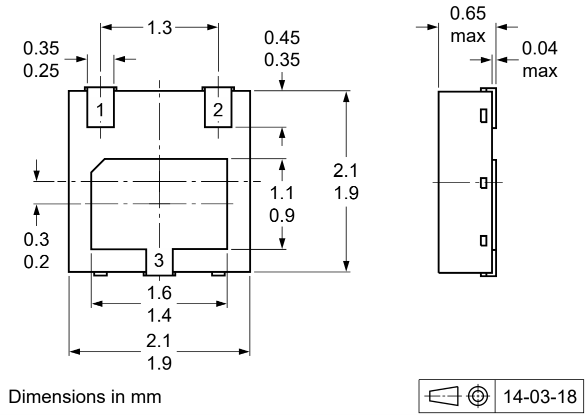


Fig. 16. Package outline DFN2020D-3 (SOT1061D)

13. Soldering

Footprint information for reflow soldering of DFN2020D-3 package **SOT1061D**

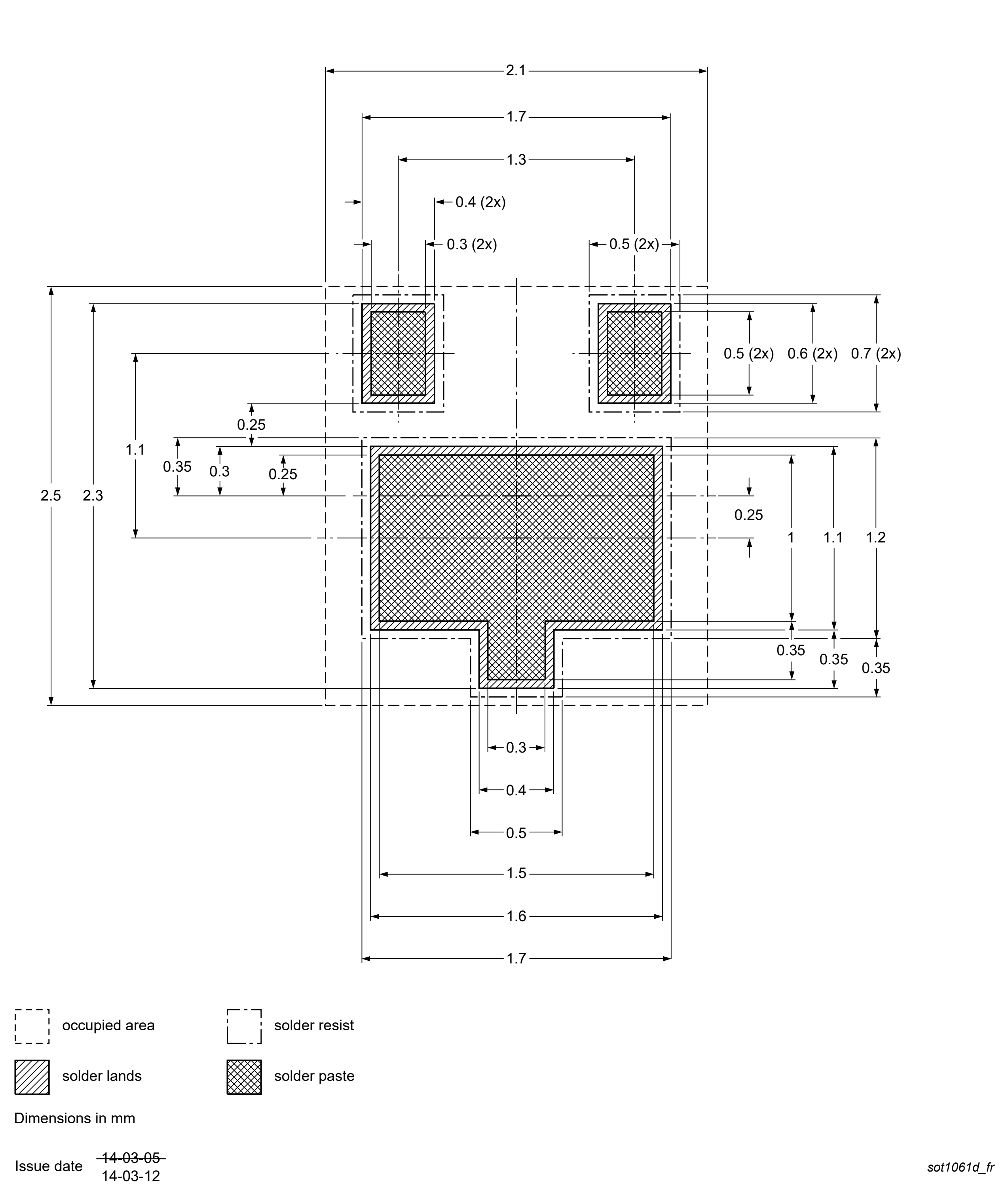


Fig. 17. Reflow soldering footprint for DFN2020D-3 (SOT1061D)

14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PBSS5250PAS-Q v.1	20240516	Product data sheet	-	-

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.
[2] The term 'short data sheet' is explained in section "Definitions".
[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the internet at https://www.nexperia.com.

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